

## Loctite® 3445 1 component fusible solder filler Anisotropic Epoxy Adhesive

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy, Electrically Conductive

### Material Notes:

Electrically Conductive Bonding and Encapsulants and Underfills Loctite® Electrically Conductive Adhesives are used in a variety of applications where electrical connectivity is needed, providing a conductive path where traditional methods such as solder, are not practical. Electrically Conductive Adhesives are ideal for attaching temperature sensitive components, or providing electrical interconnections on non-solderable substrates, such as plastic and glass. Loctite offers a complete line of electrically conductive adhesives to meet almost any need including: flexible, heat cure, room temperature cure, screen printable, high adhesion, and rapid cure. COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate. Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds. Loctite® 3445 1 component fusible solder filler Anisotropic Epoxy Adhesive A fusible solder-filled epoxy for higher current applications such as power circuit applications, flex circuit interconnect, TAB interconnect, smart cards, and COB. Cure Type: Heat Bonding Type: Epoxy

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Loctite-3445-1-component-fusible-solder-fillerAnisotropic-Epoxy-Adhesive.php](http://www.lookpolymers.com/polymer_Loctite-3445-1-component-fusible-solder-fillerAnisotropic-Epoxy-Adhesive.php)

Physical Properties	Metric	English	Comments
Density	1.70 g/cc	0.0614 lb/in <sup>3</sup>	

Thermal Properties	Metric	English	Comments
CTE, linear	<= 50.0 µm/m-°C	<= 27.8 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Glass Transition Temp, Tg	120 °C	248 °F	

Processing Properties	Metric	English	Comments
Cure Time	1.00 min	0.0167 hour	60 sec. @ 180°C under 100 psi load
Shelf Life	6.00 Month	6.00 Month	shelf life at 5°C

## Contact Songhan Plastic Technology Co.,Ltd.

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